

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	:	Park <i>et al.</i>
Appl. No.	:	10/500,494
Filed	:	December 27, 2004
For	:	METHOD OF FORMING COPPER INTERCONNECTIONS FOR SEMICONDUCTOR INTEGRATED CIRCUITS ON A SUBSTRATE
Examiner	:	Thanh V. Pham
Group Art Unit	:	2823

**AMENDMENTS AND RESPONSE TO OFFICE ACTION**

**Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on March 6, 2007, please amend the above-captioned application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.